

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC4219CDHC-12#PBF

(Engineering Calculation)

DFN 5mm X 3mm Exp. Pad

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TOTAL MASS (g): 0.037968

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001489	1000000	29217.282812		
Die Coat	Dow Corning	Silicone	69830-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.017069	974800.0625	449562.8125		
		Iron (Fe)	7439-89-6	0.000411	23500	10824.9042969		
		Phosphorus (P)	7723-14-0	0.000015	850	395.069549561		
		Zinc (Zn)	7440-66-6	0.000015	850	395.069549561		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
			Lead Frame Total:		0.017516	1000000	461177.84375	
Plating	PMI	Enter. Plating Pb	7439-92-1	0.000000	0	0		
		Enter. Plating Sn	7440-31-5	0.000817	1000000	21518.1757812		
			External Plating Total:	0.000817	1000000	21518.1757812		
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000391	1000000	10298.1464844		
			Internal Plating Total:	0.000391	1000000	10298.1464844		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000008	50000	210.70375061		
		Iridium (Ir)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000049	300000	1290.5604248		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000107	650000	2818.1628418		
			Die Attach Total:	0.000164	1000000	4319.42724609		
		Encapsulation	MULTIAROMATIC RESIN B/SB-FREE	Resin (EP)		0.002274	130000	59892.546875
				Bromine (Br)	40039-93-8	0.000000	0	0
Silica (SiO2)	60676-86-0			0.015041	860000	3961.4940625		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000175	10000	4609.14453125		
	Encapsulation Total:	0.017490	1000000	460651.0625				
Bond Wire Estimated	APW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000107	1000000	2818.1628418		

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